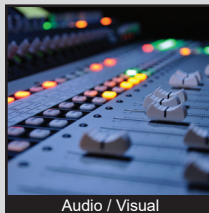


TL3336 SERIES TACT SWITCH

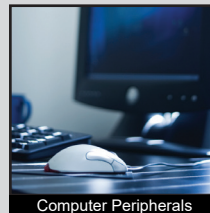
ANTI-VANDAL SWITCHES
 DETECTOR SWITCHES
 DIP SWITCHES
 KEYLOCK SWITCHES
 NAVIGATION SWITCHES
 PUSHBUTTON SWITCHES
 ROCKER SWITCHES
 ROTARY SWITCHES
 SLIDE SWITCHES
 SNAP ACTION SWITCHES
TACTILE SWITCHES
 TOGGLE SWITCHES
 CAP OPTIONS



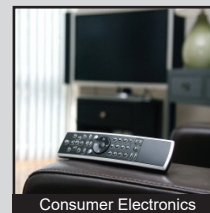
APPLICATIONS / MARKETS



Audio / Visual



Computer Peripherals



Consumer Electronics



Instrumentation



Medical Equipment



Telecommunication

RoHS

SPECIFICATIONS

Contact Arrangement: SPST Off - (On)
Contact Rating: 12VDC, 50mA
Contact Resistance: 100mΩ Max. (Initial)
Insulation Resistance: 100MΩ Min. at 100VDC
Dielectric Strength: 250VAC for 1 Minute
Electrical Life: 100,000 Cycles
Operating Temperature: -20°C to 70°C
Operating Force: 160gf ± 50gf
Travel: 0.35mm
Dust/Moisture Protection: IP67
Bounce: 10m sec. max.

FEATURES & BENEFITS

- 100,000 cycle life expectancy
- Tape and Reel packaging
- IP67 ratings
- Right angle surface mount design

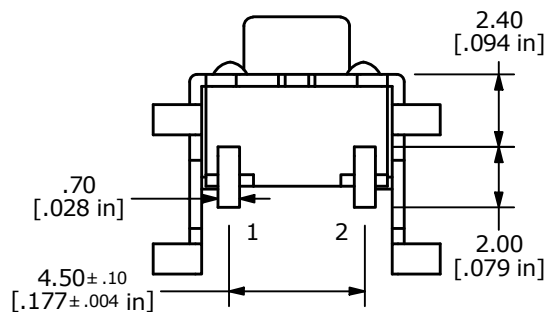
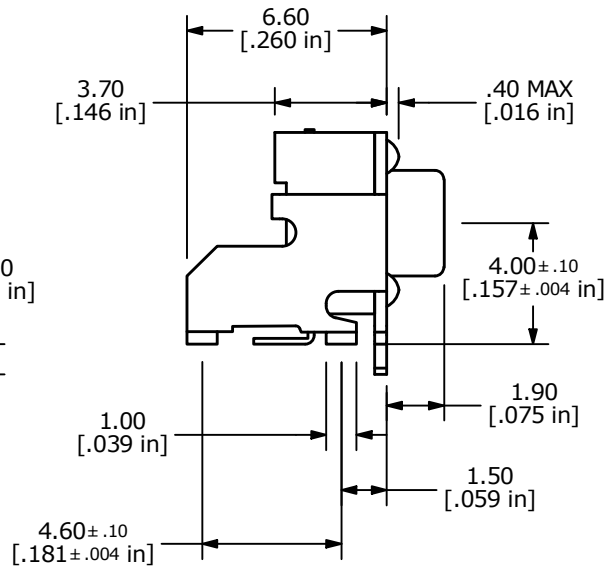
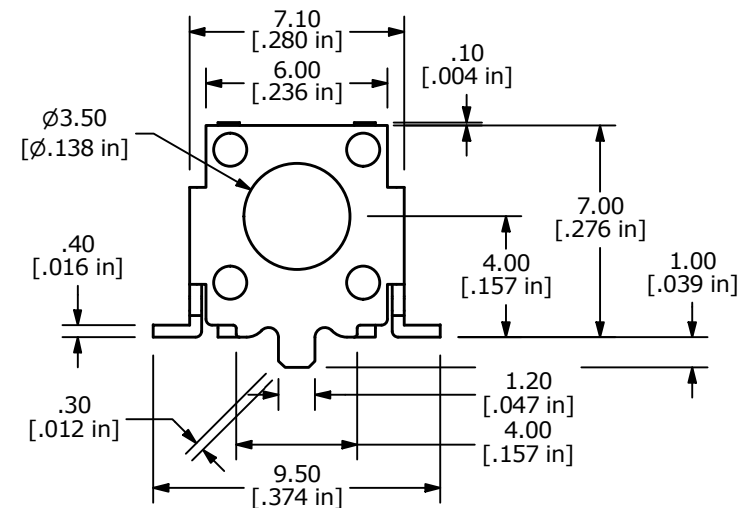
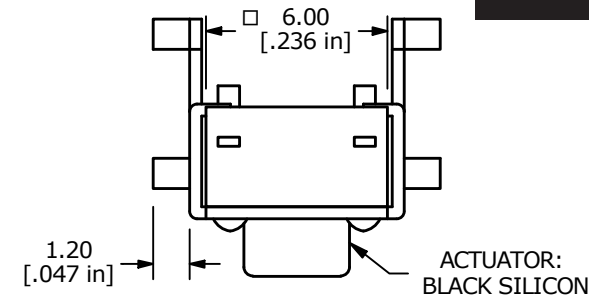
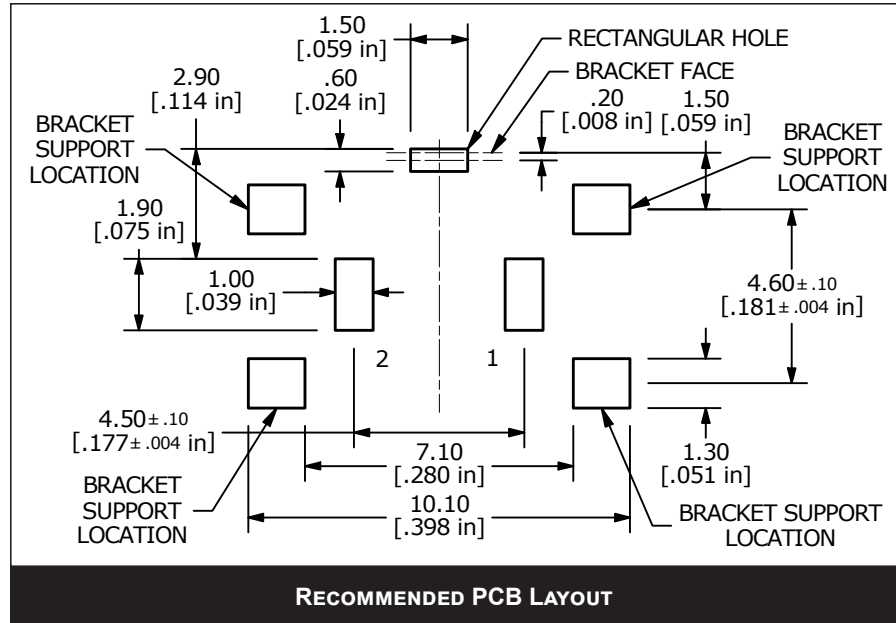
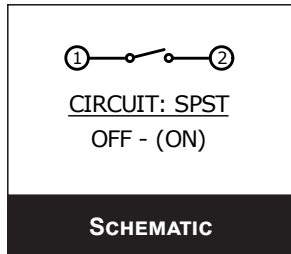
PART NUMBER CONFIGURATOR

Series	Model	Actuator "L" Dimension	Actuation Force	Contact Material
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Specifications subject to change without notice 3.30.2021

TL3336 SERIES TACT SWITCH

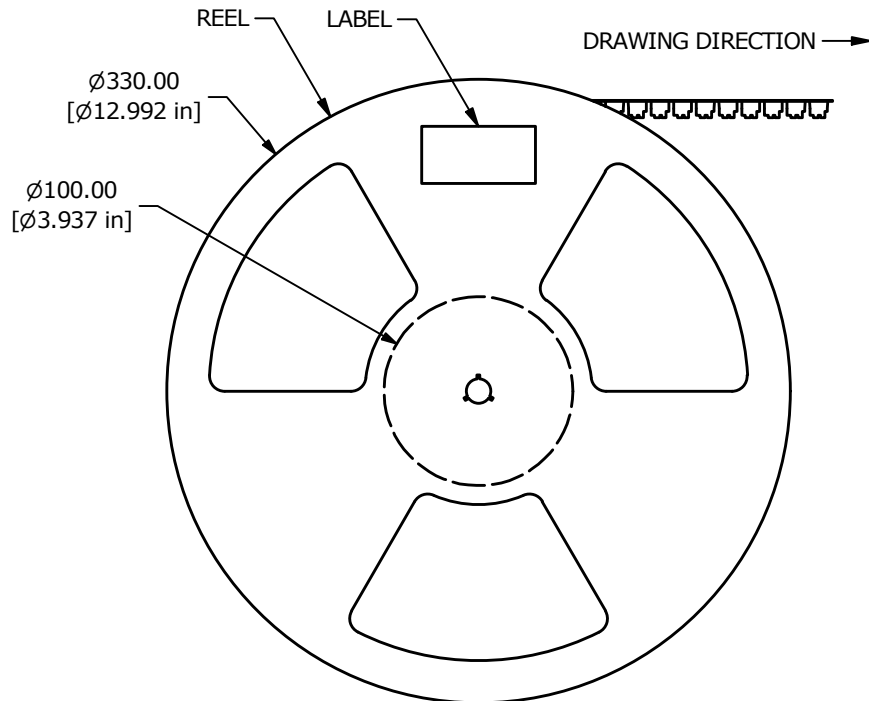
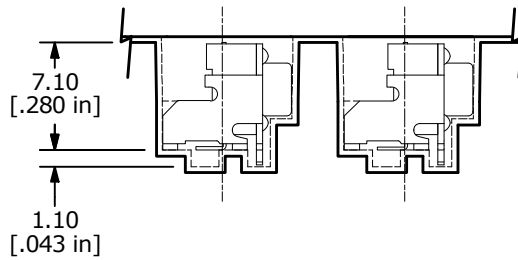
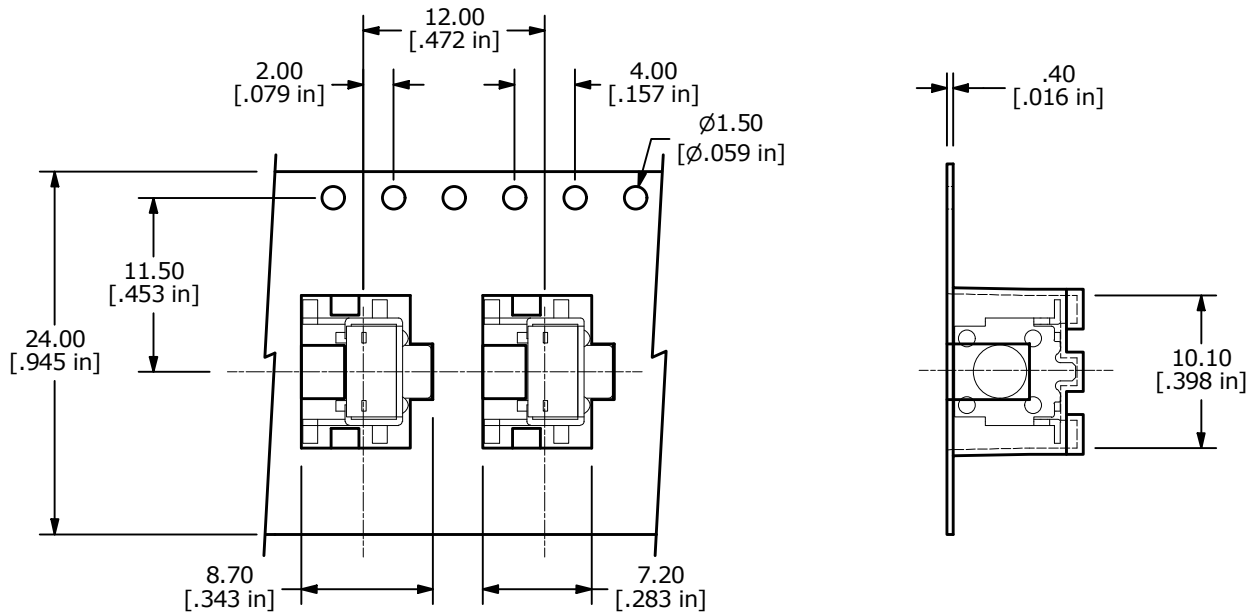
BODY DIMENSIONS



ANTI-VANDAL SWITCHES
 DETECTOR SWITCHES
 DIP SWITCHES
 KEYLOCK SWITCHES
 NAVIGATION SWITCHES
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TL3336 SERIES TACT SWITCH

BODY DIMENSIONS TAPE AND REEL



RECOMMENDED SOLDER PROCESS

Most contamination problems can be prevented by exercising care during the cleaning and soldering process. Care should be taken not to immerse or spray unsealed switches during flux removal. Contact E-Switch for specific soldering recommendations and specifications not shown. Generalized soldering procedures are outlined below.

“TYPICAL” SMT REFLOW (Pb and Pb-Free)

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average Ramp-Up Rate (T _{smax} to T _p)	3 °C/second max.	3 °C/second max.
Preheat		
-Temperature Min (T _{smin})	100 °C	150 °C
-Temperature Max (T _{smax})	150 °C	200 °C
-Time (t _{smin} to t _{smax})	60-120 seconds	60-180 seconds
Time Maintained above:		
-Temperature (T _L)	183 °C	217 °C
-Time (t _L)	60-150 seconds	60-150 seconds
Time within 5 °C of actual Peak Temperature (t _p)	10-30 seconds	20-40 seconds
Ramp-Down Rate	6 °C/second max.	6 °C/second max.
Time 25 °C to Peak Temperature	6 minutes max.	8 minutes max.

Note 1: All temperatures refer to topside of the package, measured on the package surface.

